

Appl. No. : 10/705,824
 Filed : November 13, 2003

AMENDMENTS TO THE CLAIMS

Claims 1-16 were previously cancelled.

17. (Original) A method for manufacturing an optical interference display unit disposed on a substrate, the method comprising:

- forming a first electrode on the substrate;
- forming a sacrificial layer on the first electrode;
- forming at least two openings in the sacrificial layer and the first electrode to define a position of the optical interference display unit;
- forming a support in each of the openings and at least one arm on the support, wherein the support and the at least one arm form a post;
- forming a second electrode on the sacrificial layer and the at least one arm;
- performing a thermal process to treat the post; and
- removing the sacrificial layer.

18. (Presently amended) The method for manufacturing an optical interference display unit of claim 17, wherein the ~~photosensitive material layer~~ post ~~is~~ comprises a photoresist.

19. (Presently amended) The method for manufacturing an optical interference display unit of claim 17, wherein the post ~~is made from~~ comprises photosensitive or non-photosensitive materials.

20. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the step of forming the post comprises:

- forming a photosensitive material layer to fill the openings and cover the sacrificial layer; and
- patterning the photosensitive material layer to form the support in each of the openings and at least one arm on the support, wherein the support and the at least one arm form the post.

21. (Original) The method for manufacturing an optical interference display unit of claim 20, wherein the step of patterning the photosensitive material layer includes a photolithographic process.

22. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the step of forming the support further comprises:

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forming a non-photosensitive material layer to fill the openings and cover the sacrificial layer; and

patterning the non-photosensitive material layer to form the support in each of the openings and the at least one arm on the support by a photolithographic etching process, wherein the support and the at least one arm form the post.

23. (Presently amended) The method for manufacturing an optical interference display unit of claim 17, wherein the thermal process iscomprises baking.

24. (Presently amended) The method for manufacturing an optical interference display unit of claim 17, wherein the thermal process results in ~~makes the at least one arm to generate displacement of at least one arm~~ due to stress.

25. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the first electrode comprises:

the substrate;
an absorption layer; and
a dielectric layer.

26. (Original) The method for manufacturing an optical interference display unit of claim 25, wherein the substrate is a transparent material.

27. (Presently amended) The method for manufacturing an optical interference display unit of claim 25, wherein the dielectric layer ~~is made from~~ comprises silicon oxide, silicon nitride or metal oxide.

28. (Presently amended) The method for manufacturing an optical interference display unit of claim 25, wherein the absorption layer ~~is made from~~ comprises metal.

29. (Presently amended) The method for manufacturing an optical interference display unit of claim 25, wherein the substrate ~~is made from~~ comprises ITO glass or IZO glass.

30. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the first electrode and the second electrode are selected from a group consisting of narrowband mirrors, broadband mirrors, non-metal mirrors, metal mirrors and the combination thereof.

31. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the second electrode is a deformable electrode.

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32. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the second electrode is a movable electrode.

33. (Original) The method for manufacturing an optical interference display unit of claim 17, wherein the second electrode at least comprises opaque materials or semi-transparent materials.

34. (Presently amended) The method for manufacturing an optical interference display unit of claim 33, wherein the semi-transparent materials are comprises ITO glass or IZO glass.

35. (Presently amended) The method for manufacturing an optical interference display unit of claim 17, wherein the posts-supports are made from comprise a photoresist photosensitive material.

36. (New) The method for manufacturing an optical interference display unit of claims 20 or 21, wherein the photosensitive material layer comprises a photoresist.